

Features:

- n Isolated mounting base 3000V~
- n Pressure contact technology with Increased power cycling capability
- n Space and weight saving

Typical Applications:

- n Inverter
- n Inductive heating
- n Chopper

V _{RRM}	Type & Outline
600V	MZx400-06-406F3
800V	MZx400-08-406F3
1000V	MZx400-10-406F3
1200V	MZx400-12-406F3
1400V	MZx400-14-406F3
1600V	MZx400-16-406F3
1800V	MZx400-18-406F3
1800V	MZx400-18-406F3G

MZx stands for any type of **MZC, MZA, MZK**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =60°C	150			400	A
I _{F(RMS)}	RMS forward current					628	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			70	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =0.6V _{RRM}	150			8.30	kA
I ² t	I ² t for fusing coordination					344	A ² s*10 ³
V _{FO}	Threshold voltage		150			1.0	V
r _F	Forward slope resistance					0.85	m
V _{FM}	Peak forward voltage	I _{FM} =1200A	25			2.1	V
t _{rr}	Reverse recovery time	I _{FM} =300A, tp=4000μs, -di/dt=20A/μs, V _R =50V	150		4.0		μs
			25		2.0		μs
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled per chip				0.130	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled per chip				0.040	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(MAX)		3000			V
F _m	Terminal connection torque(M10)			10.0		12.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				1580		g
Outline	406F3						

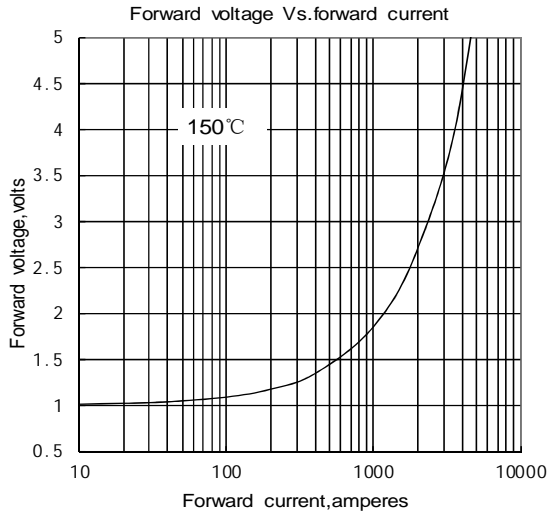


Fig.1

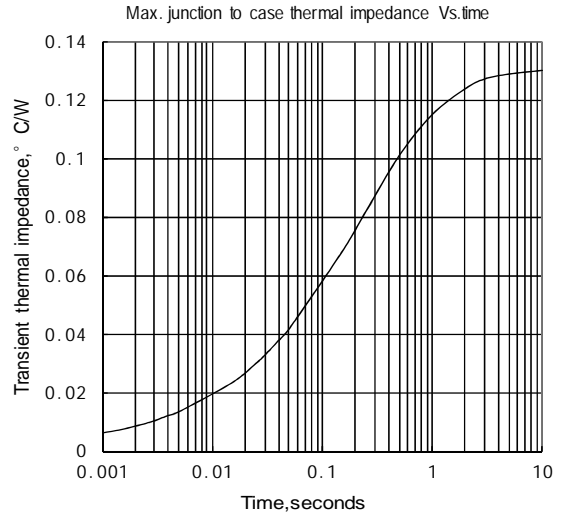


Fig.2

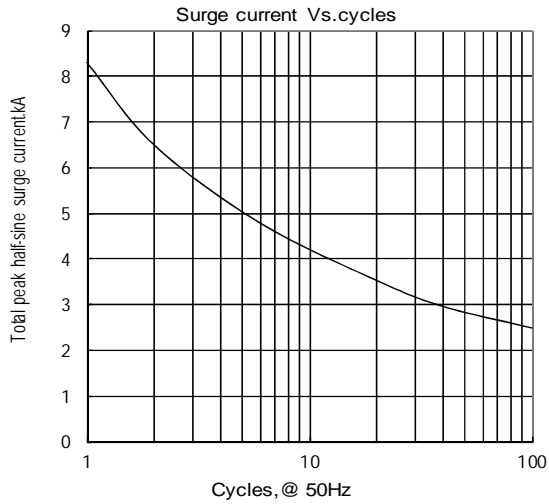


Fig.3

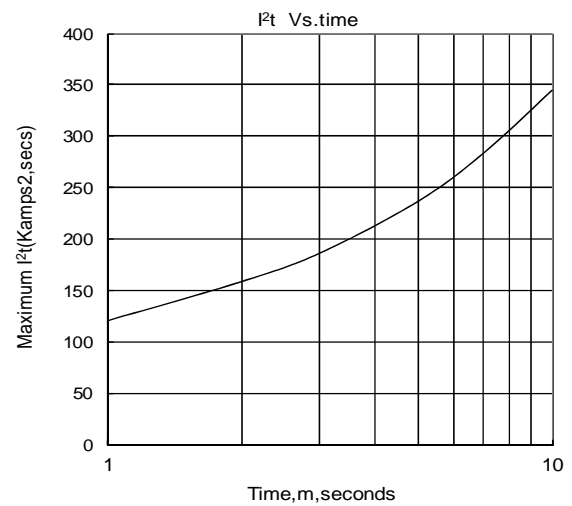
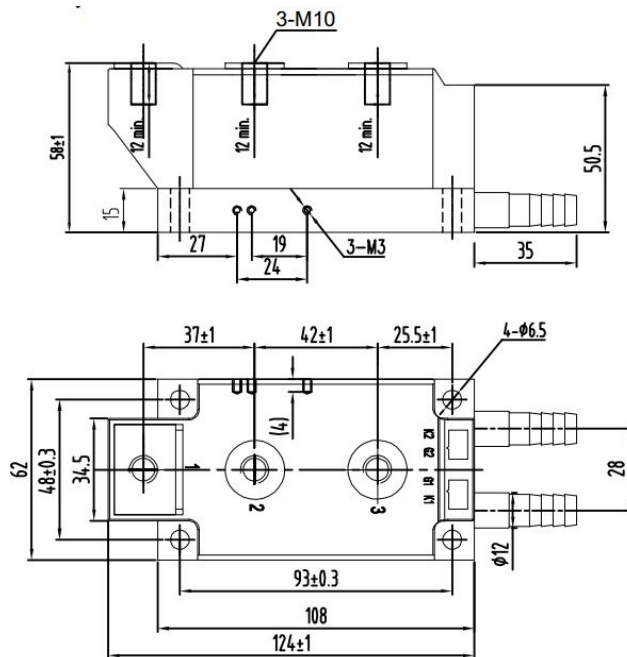


Fig.4

Outline:



Unmarked dimensional tolerance: ±0.5mm

TECHSEM reserves the right to change specifications without notice.

